



## PATENT ABSTRACTS OF JAPAN

(11) Publication number: **11195327 A**(43) Date of publication of application: **21.07.99**

(51) Int. Cl.

**H01B 7/00**  
**B29C 51/10**  
**B29C 51/12**  
**B60R 16/02**  
**H01B 13/00**  
**// B29L 31:34**  
**B29L 31:58**

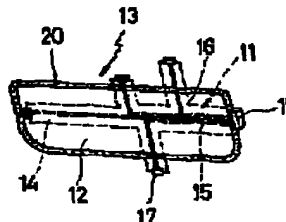
(21) Application number: **10001123**(22) Date of filing: **06.01.98**(71) Applicant: **YAZAKI CORP**

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**(54) WIRE HARNESS AND ITS MANUFACTURE****(57) Abstract:**

**PROBLEM TO BE SOLVED:** To simply lay out a wire harness and to lessen the number of part items by integrating it with a sealing screen.

**SOLUTION:** This wire harness 13 is so constituted that a circuit 15 is printed on one side of a film 14, thereafter a circuit body 11 prepared with a marginal part 16 of the film 14 around the circuit 15 is formed by punching out the film 14 along the circuit 15, and a sealing screen 12 covers a circuit formed surface of the circuit body 11 and it is stuck fast to agglutinate them, then the circuit body 11 is integrated with the sealing screen 12. Because of integration with the sealing screen, the number of components is lessened, and the circuit body 11 of the wire harness 13 can be installed only by loading the sealing screen 12 onto a door inner panel.



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